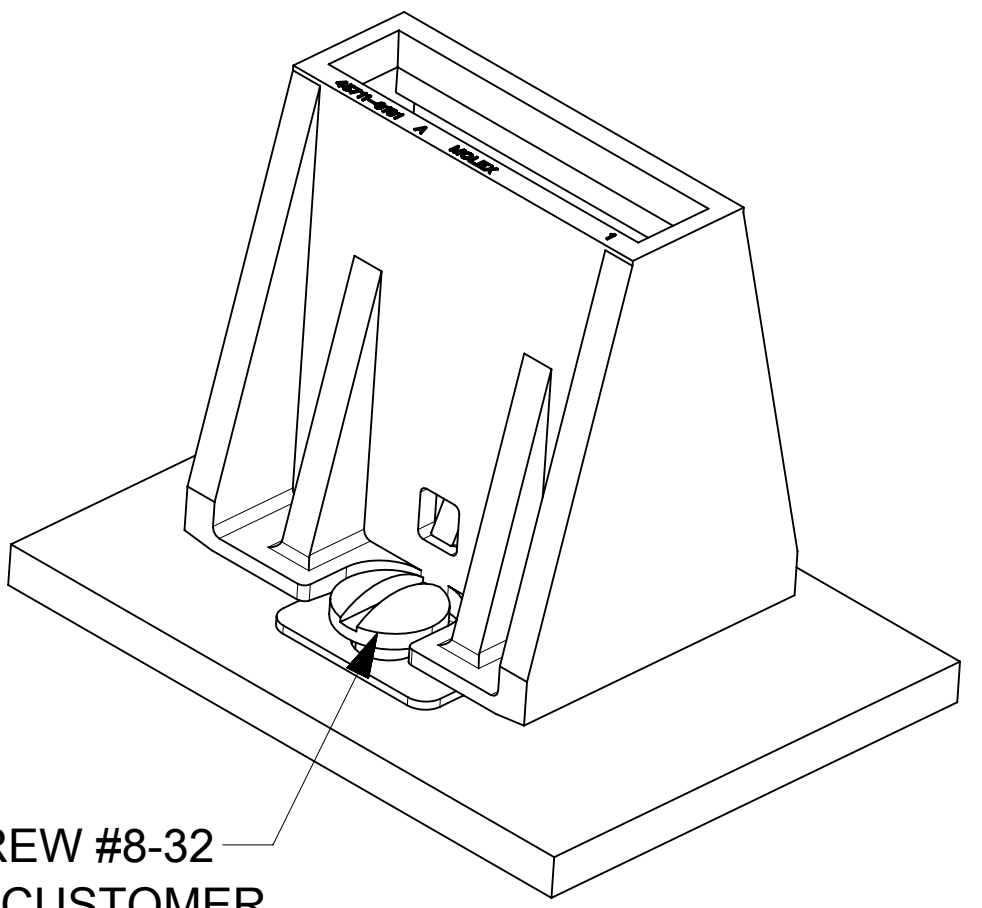
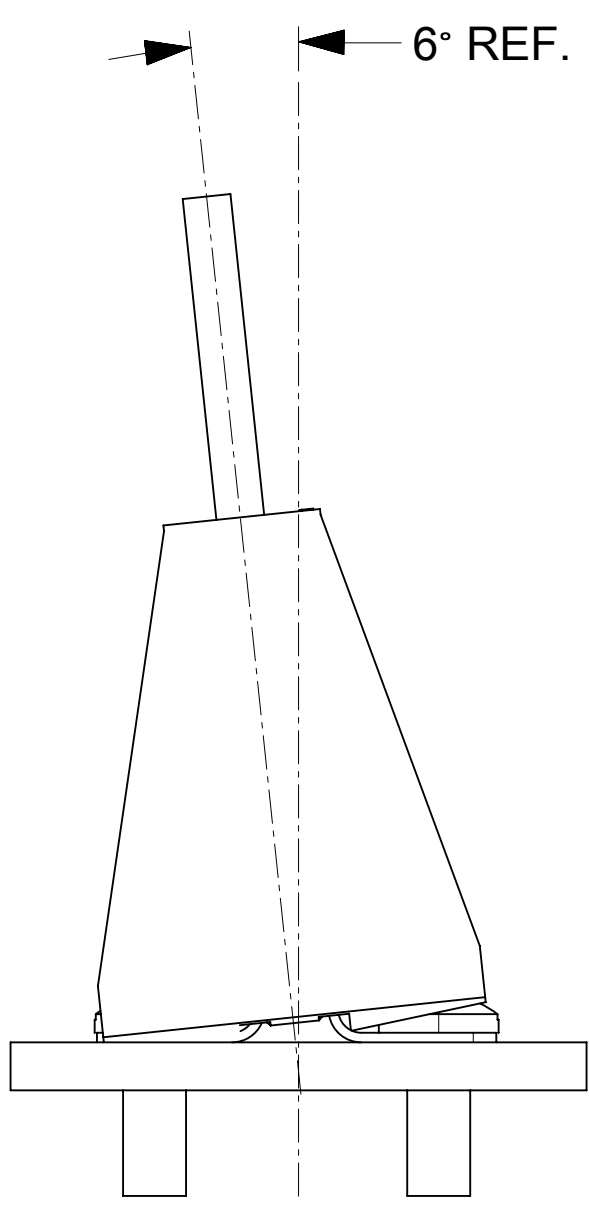
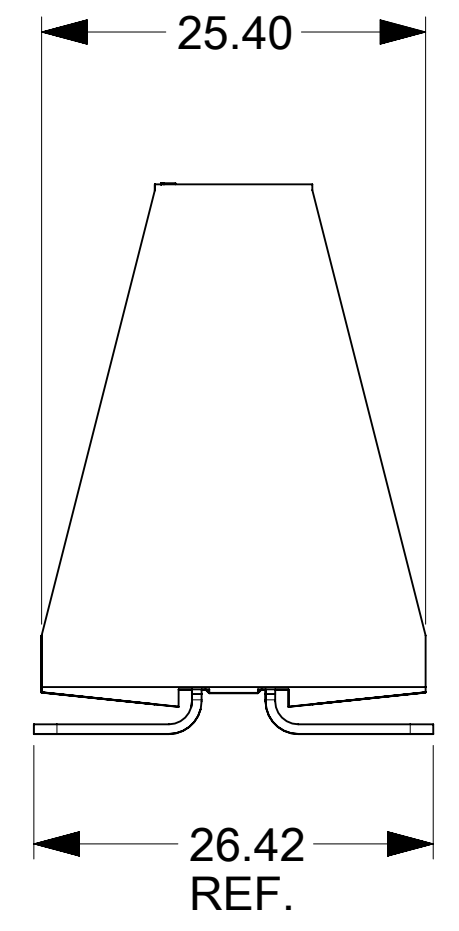
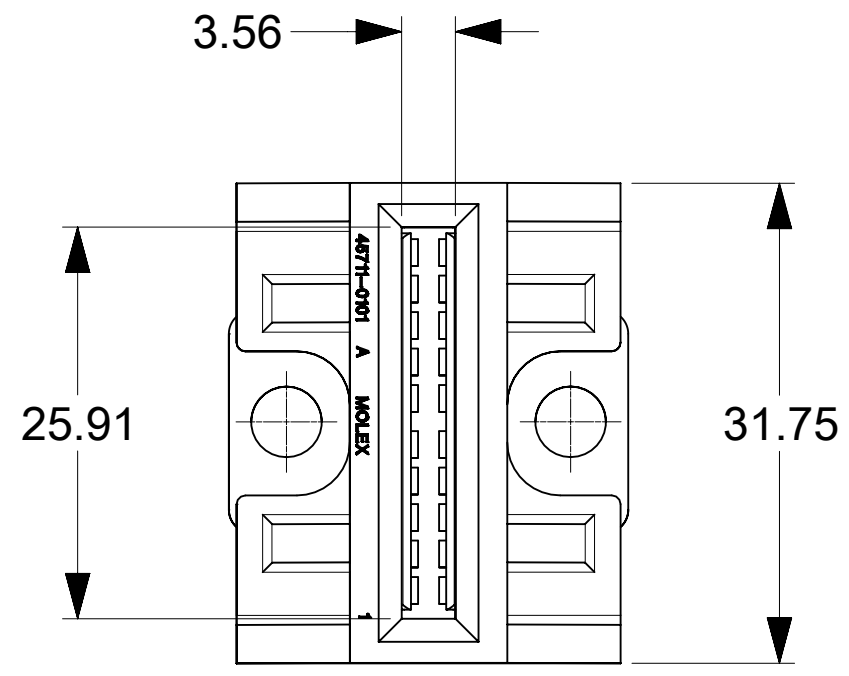
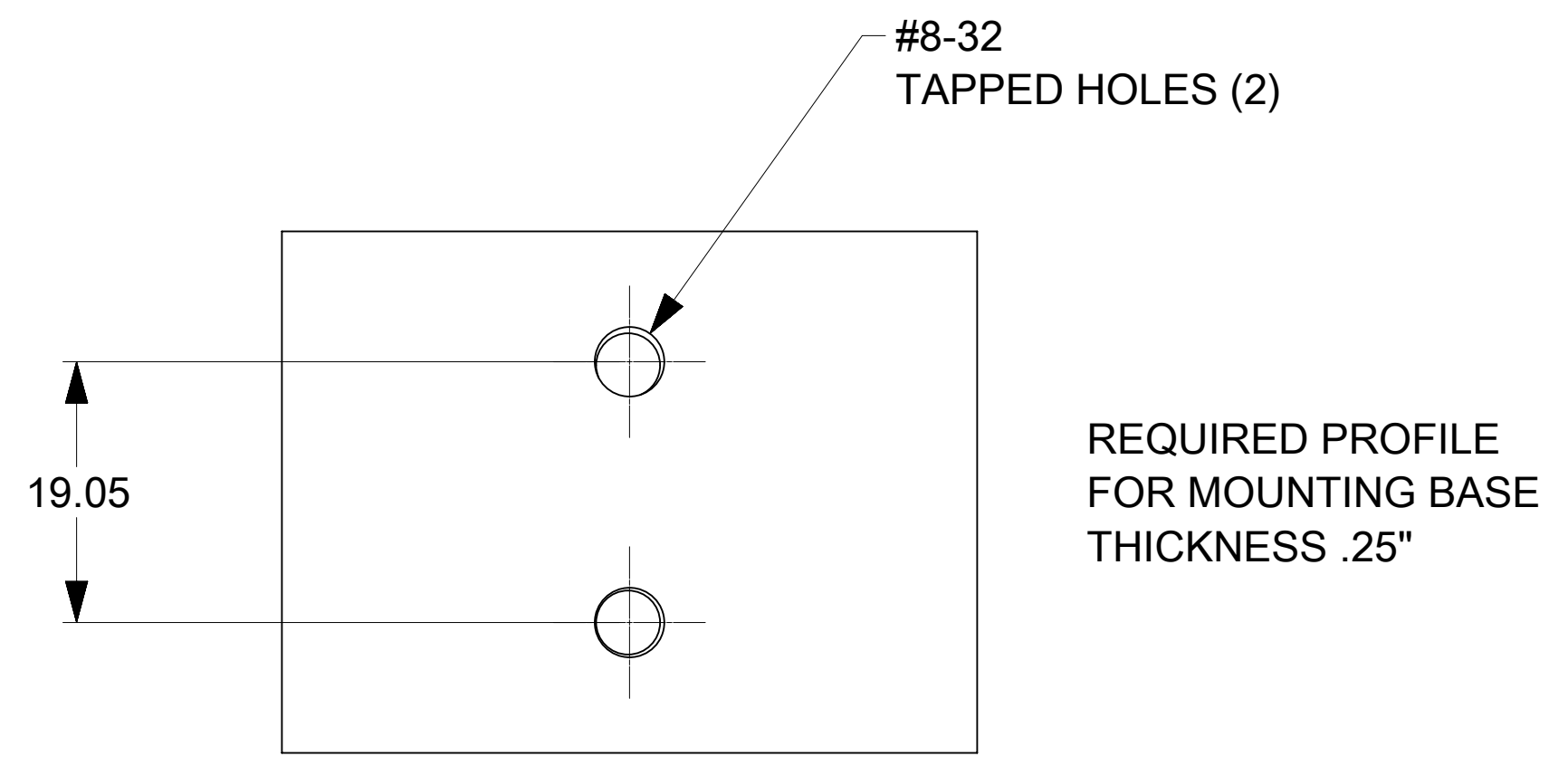
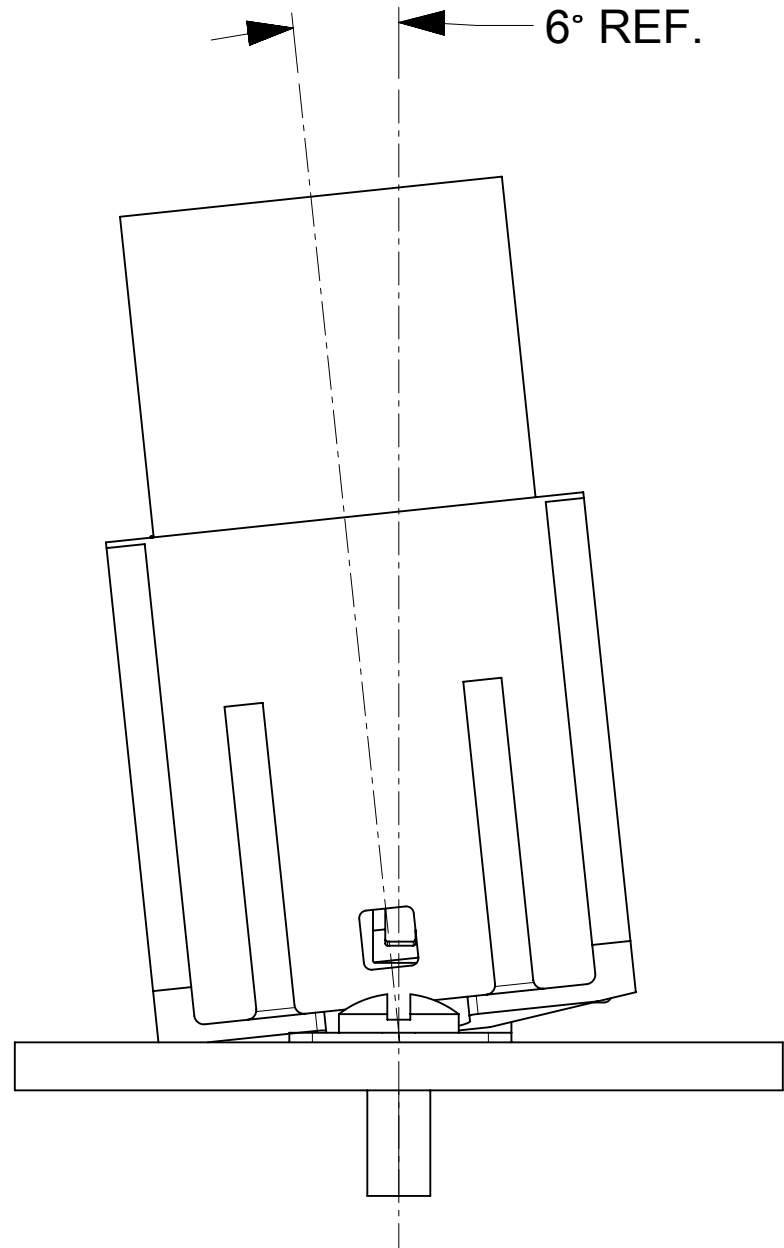
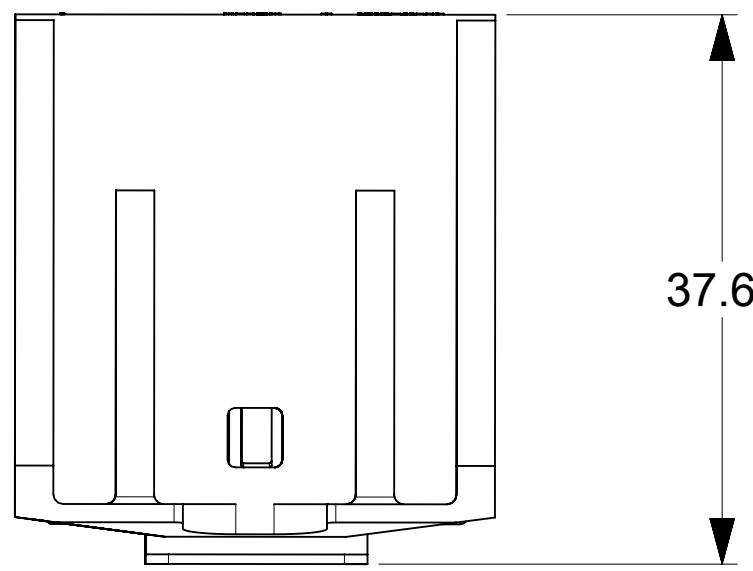


MATERIAL NUMBER	PLATING DETAILS	PRODUCT SPEC.
457111000	GOLD PLATED: 30 μINCHES GOLD ON CONTACT AREA 100 μINCHES TIN ON TAILS, OVER 50 μINCHES NICKEL PLATE OVERALL.	PS-45711-001
457112000	SILVER PLATED: 125 μINCHES SEMI-BRIGHT SILVER ON CONTACT AREA 100 μINCHES TIN ON TAILS, OVER 50 μINCHES NICKEL PLATE OVERALL.	

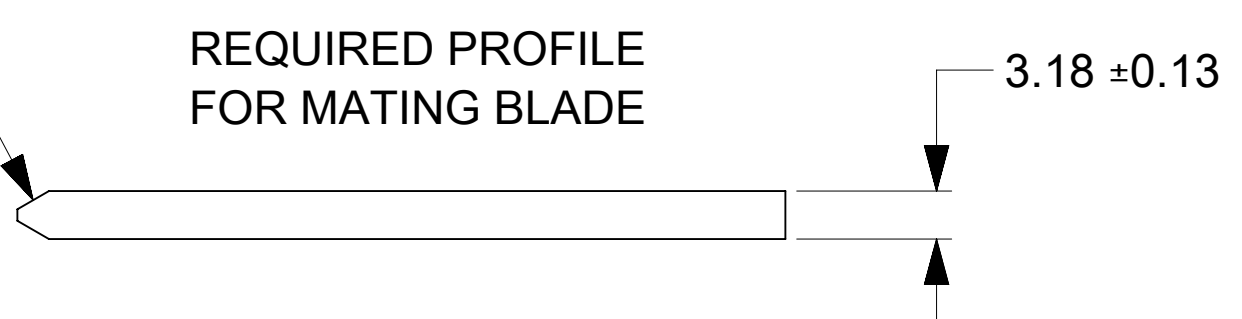


MACHINE SCREW #8-32
SUPPLIED BY CUSTOMER
(2 REQUIRED)



REQUIRED PROFILE
FOR MOUNTING BASE
THICKNESS .25"

ON THE MATING SIDE
CHAMFER/RADIUS
RECOMMENDED



REQUIRED PROFILE
FOR MATING BLADE

13.72 MIN.
PLATING AREA.
GOLD OR SILVER
(SEE NOTE 3)



- NOTE:
- MATERIALS:
TERMINALS: HIGH CONDUCTIVITY COPPER ALLOY.
HOUSING: RoHS COMPLIANT 94V-0 THERMOPLASTIC.
 - PACKAGED PER MOLEX PACKAGING SPEC. PK-45711-000.
 - SILVER PLATING IS AN ACCEPTABLE ALTERNATIVE FOR BUS BAR APPLICATION.

CONNECTOR IS ALLOWED
TO "LEAN" 6° IN EITHER DIRECTION
(AS SHOWN)

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION											
DIMENSION UNITS		SCALE		CURRENT REV DESC:							
mm		2:1									
GENERAL TOLERANCES (UNLESS SPECIFIED)				EC NO: 659330							
		MM		INCH		DRWN: GSHARMA 2020/06/30					
4 PLACES		±		±		CHK'D: GSHARMA 2021/03/26					
3 PLACES		±		±		APPR: HTHYAGARAJ 2021/04/08					
2 PLACES		± 0.25		±		INITIAL REVISION:					
1 PLACE		± 0.25		±		DRWN: SBB 11/19/04					
0 PLACES		±		±		APPR:					
ANGULAR TOL		± 1.0°		±		THIRD ANGLE PROJECTION					
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				DRAWING		SERIES		MATERIAL NUMBER		CUSTOMER	
				D-SIZE		45711		SEE TABLE		GENERAL MARKET	
DOCUMENT STATUS				DOC TYPE		DOC PART		REVISION		SHEET NUMBER	
P1				PSD		001		D		1 OF 1	
RELEASE DATE		2021/04/08		16:54:04							